### 3ME2 Series

**Customer:**

**Customer Part Number:**

**Innodisk Part Number:**

**Innodisk Model Name:**

**Date:**

<table>
<thead>
<tr>
<th>Innodisk Approver</th>
<th>Customer Approver</th>
</tr>
</thead>
</table>
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<td>First Released</td>
<td>Feb., 2015</td>
</tr>
<tr>
<td>Rev 1.0</td>
<td>1. Update TBW</td>
<td>Mar., 2015</td>
</tr>
<tr>
<td>Rev 1.1</td>
<td>Update performance</td>
<td>Mar., 2015</td>
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<tr>
<td>Rev 1.2</td>
<td>Add 32GB Information</td>
<td>May, 2015</td>
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<tr>
<td>Rev 1.3</td>
<td>Update performance</td>
<td>May, 2015</td>
</tr>
<tr>
<td>Rev 2.0</td>
<td>Add Toshiba 15nm</td>
<td>Aug., 2016</td>
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1. Product Overview

1.1 Introduction of Innodisk SATA Slim 3ME2

Innodisk SATA Slim 3ME2 provides a totally brand new highly cost-effective SSD solution with good performance and longer lifespan. SATA Slim 3ME2 is a perfect substitute for traditional HDD, which are applied with an evolved L^2 Wear Leveling Architecture, and significantly improves SSD random data transfer rate and lifespan. Furthermore, SATA Slim 3ME2 supports TRIM for windows 7, it can improves performance when deleting files.

SATA Slim 3ME2 provides high capacity flash memory within JEDEC MO-297 spec., which electrically compatible with Serial ATA (SATA) standard, and supports SATA III standard (6.0GHz) with high performance. It has good performance; no latency time and small seek time. It effectively reduces the booting time of operation system and the power consumption is less than hard disk drive (HDD).

1.2 Product View and Models

Innodisk SATA Slim 3ME2 is available in follow capacities within MLC flash ICs.

- SATA Slim 8GB
- SATA Slim 16GB
- SATA Slim 3ME2 32GB
- SATA Slim 3ME2 64GB
- SATA Slim 3ME2 128GB
- SATA Slim 3ME2 256GB

Figure 1: Innodisk SATA Slim 3ME2
1.3 SATA Interface
SATA Slim 3ME2 supports SATA III interface, and backward compliant with Serial ATA Gen 1, Gen 2 and Gen 3 specification (Gen 3 supports 1.5Gbps /3.0Gbps/6.0Gbps data rate).

1.4 Capacity
Innodisk SATA Slim 3ME2 provides unformatted 8GB, 16GB, 32GB, 64GB, 128GB, and 256GB capacities within MLC Flash IC.

1.5 MO-297 Form Factor
SATA Slim 3ME2 has a compact design 54.0mm (W) x 39.0mm (L) x 4.0mm (H) without metal material case, and is easy for installation.
2. Product Specifications

2.1 Capacity and Device Parameters
SATA Slim 3ME2 device parameters are shown in Table 1.

<table>
<thead>
<tr>
<th>Capacity</th>
<th>LBA</th>
<th>Cylinders</th>
<th>Heads</th>
<th>Sectors</th>
<th>User Capacity(MB)</th>
</tr>
</thead>
<tbody>
<tr>
<td>8GB</td>
<td>15649200</td>
<td>15255</td>
<td>16</td>
<td>63</td>
<td>7,641</td>
</tr>
<tr>
<td>16GB</td>
<td>31277232</td>
<td>16383</td>
<td>16</td>
<td>63</td>
<td>15,272</td>
</tr>
<tr>
<td>32GB</td>
<td>62533296</td>
<td>16383</td>
<td>16</td>
<td>63</td>
<td>30533</td>
</tr>
<tr>
<td>64GB</td>
<td>125045424</td>
<td>16383</td>
<td>16</td>
<td>63</td>
<td>61057</td>
</tr>
<tr>
<td>128GB</td>
<td>250069680</td>
<td>16383</td>
<td>16</td>
<td>63</td>
<td>122104</td>
</tr>
<tr>
<td>256GB</td>
<td>500118192</td>
<td>16383</td>
<td>16</td>
<td>63</td>
<td>244198</td>
</tr>
</tbody>
</table>

2.2 Performance
Burst Transfer Rate: 6.0Gbps

<table>
<thead>
<tr>
<th>Capacity</th>
<th>32GB</th>
<th>64GB</th>
<th>128GB</th>
<th>256GB</th>
</tr>
</thead>
<tbody>
<tr>
<td>Micron L95</td>
<td>Sequential Read (max.)</td>
<td>220 MB/s</td>
<td>440 MB/s</td>
<td>440 MB/s</td>
</tr>
<tr>
<td></td>
<td>Sequential Write (max.)</td>
<td>40 MB/s</td>
<td>80 MB/s</td>
<td>160 MB/s</td>
</tr>
<tr>
<td>4KB Random Read (QD32)</td>
<td>1,000 IOPS</td>
<td>21,000 IOPS</td>
<td>30,000 IOPS</td>
<td>29,000 IOPS</td>
</tr>
<tr>
<td>4KB Random Write (QD32)</td>
<td>1,000 IOPS</td>
<td>21,000 IOPS</td>
<td>40,000 IOPS</td>
<td>39,000 IOPS</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Capacity</th>
<th>8GB</th>
<th>16GB</th>
<th>32GB</th>
<th>64GB</th>
<th>128GB</th>
<th>256GB</th>
</tr>
</thead>
<tbody>
<tr>
<td>Toshiba 15nm</td>
<td>Sequential Read (max.)</td>
<td>140 MB/s</td>
<td>140 MB/s</td>
<td>280 MB/s</td>
<td>500 MB/s</td>
<td>510 MB/s</td>
</tr>
<tr>
<td></td>
<td>Sequential Write (max.)</td>
<td>25 MB/s</td>
<td>25 MB/s</td>
<td>50 MB/s</td>
<td>100 MB/s</td>
<td>190 MB/s</td>
</tr>
<tr>
<td>4KB Random Read (QD32)</td>
<td>7,300 IOPS</td>
<td>6,800 IOPS</td>
<td>13,700 IOPS</td>
<td>26,000 IOPS</td>
<td>32,900 IOPS</td>
<td>34,500 IOPS</td>
</tr>
<tr>
<td>4KB Random Write (QD32)</td>
<td>3,800 IOPS</td>
<td>3,600 IOPS</td>
<td>10,200 IOPS</td>
<td>24,000 IOPS</td>
<td>47,600 IOPS</td>
<td>47,000 IOPS</td>
</tr>
</tbody>
</table>

Note: Based on CrystalDiskMark 3.03 with file size 1000MB
2.3 Electrical Specifications

2.3.1 Power Requirement

Table 3: Innodisk SATA Slim 3ME2 Power Requirement

<table>
<thead>
<tr>
<th>Item</th>
<th>Symbol</th>
<th>Rating</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input voltage</td>
<td>$V_{IN}$</td>
<td>+5 DC +- 5%</td>
<td>V</td>
</tr>
</tbody>
</table>

2.3.2 Power Consumption

Table 4: Power Consumption

<table>
<thead>
<tr>
<th>Mode</th>
<th>Power Consumption</th>
</tr>
</thead>
<tbody>
<tr>
<td>Read</td>
<td>225 mA (max.)</td>
</tr>
<tr>
<td>Write</td>
<td>335 mA (max.)</td>
</tr>
<tr>
<td>Idle</td>
<td>61 mA (max.)</td>
</tr>
<tr>
<td>DEVSLP Mode</td>
<td>3mW (min.)</td>
</tr>
<tr>
<td>Slumber Mode</td>
<td>30mW (min.)</td>
</tr>
</tbody>
</table>

* Target: SATA Slim 3ME2 256GB (Micron L95)

2.4 Environmental Specifications

2.4.1 Temperature Ranges

Table 5: Temperature range for SATA Slim 3ME2

<table>
<thead>
<tr>
<th>Temperature</th>
<th>Range</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operating</td>
<td>Standard Grade: 0°C to +70°C</td>
</tr>
<tr>
<td></td>
<td>Industrial Grade: -40°C to +85°C</td>
</tr>
<tr>
<td>Storage</td>
<td>-55°C to +95°C</td>
</tr>
</tbody>
</table>

2.4.2 Humidity

Relative Humidity: 10-95%, non-condensing

2.4.3 Shock and Vibration

Table 6: Shock/Vibration Testing for SATA Slim 3ME2

<table>
<thead>
<tr>
<th>Reliability</th>
<th>Test Conditions</th>
<th>Reference Standards</th>
</tr>
</thead>
<tbody>
<tr>
<td>Vibration</td>
<td>7 Hz to 2K Hz, 20G, 3 axes</td>
<td>IEC 68-2-6</td>
</tr>
<tr>
<td>Mechanical Shock</td>
<td>Duration: 0.5ms, 1500 G, 3 axes</td>
<td>IEC 68-2-27</td>
</tr>
</tbody>
</table>

2.4.4 Mean Time between Failures (MTBF)

Table 7 summarizes the MTBF prediction results for various SATA Slim 3ME2 configurations. The analysis was performed using a RAM Commander™ failure rate prediction.

- **Failure Rate**: The total number of failures within an item population, divided by the total
number of life units expended by that population, during a particular measurement interval under stated condition.

- **Mean Time between Failures (MTBF):** A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

<table>
<thead>
<tr>
<th>Table 7: SATA Slim 3ME2 MTBF</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Product</strong></td>
</tr>
<tr>
<td>Innodisk SATA Slim 3ME2</td>
</tr>
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</table>

2.5 CE and FCC Compatibility
SATA Slim 3ME2 conforms to CE and FCC requirements.

2.6 RoHS Compliance
SATA Slim 3ME2 is fully compliant with RoHS directive.

2.7 Reliability

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
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</thead>
<tbody>
<tr>
<td>Read Cycles</td>
<td>Unlimited Read Cycles</td>
</tr>
<tr>
<td>Wear-Leveling Algorithm</td>
<td>Support</td>
</tr>
<tr>
<td>Bad Blocks Management</td>
<td>Support</td>
</tr>
<tr>
<td>Error Correct Code</td>
<td>Support</td>
</tr>
<tr>
<td>iData Guard</td>
<td>Support</td>
</tr>
<tr>
<td>Thermal Sensor</td>
<td>Support</td>
</tr>
<tr>
<td>TBW* (Total Bytes Written)</td>
<td>Unit: TB</td>
</tr>
<tr>
<td>8GB</td>
<td>2.3</td>
</tr>
<tr>
<td>16GB</td>
<td>4.7</td>
</tr>
<tr>
<td>32GB</td>
<td>9.6</td>
</tr>
<tr>
<td>64GB</td>
<td>19.2</td>
</tr>
<tr>
<td>128GB</td>
<td>38.4</td>
</tr>
<tr>
<td>256GB</td>
<td>76.8</td>
</tr>
</tbody>
</table>

* Total bytes written is based on JEDEC 218 (Solid-State Drive Requirements and Endurance Test Method)  
** Lifespan is calculated by device written per day

2.8 Transfer Mode
SATA Slim 3ME2 support following transfer mode:  
Serial ATA III 6.0Gbps  
Serial ATA II 3.0Gbps  
Serial ATA I 1.5Gbps
# 2.9 Pin Assignment

Innodisk SATA Slim 3ME2 uses a standard SATA pin-out. See Table 8 for SATA Slim 3ME2 pin assignment.

<table>
<thead>
<tr>
<th>Name</th>
<th>Type</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>S1</td>
<td>GND</td>
<td>NA</td>
</tr>
<tr>
<td>S2</td>
<td>A+</td>
<td>Differential Signal Pair A</td>
</tr>
<tr>
<td>S3</td>
<td>A-</td>
<td></td>
</tr>
<tr>
<td>S4</td>
<td>GND</td>
<td>NA</td>
</tr>
<tr>
<td>S5</td>
<td>B-</td>
<td>Differential Signal Pair B</td>
</tr>
<tr>
<td>S6</td>
<td>B+</td>
<td></td>
</tr>
<tr>
<td>S7</td>
<td>GND</td>
<td>NA</td>
</tr>
</tbody>
</table>

**Key and Spacing separate signal and power segments**

<table>
<thead>
<tr>
<th>Name</th>
<th>Type</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>P1</td>
<td>NC</td>
<td>NA</td>
</tr>
<tr>
<td>P2</td>
<td>NC</td>
<td>NA</td>
</tr>
<tr>
<td>P3</td>
<td>NC</td>
<td>NA</td>
</tr>
<tr>
<td>P4</td>
<td>GND</td>
<td>NA</td>
</tr>
<tr>
<td>P5</td>
<td>GND</td>
<td>NA</td>
</tr>
<tr>
<td>P6</td>
<td>GND</td>
<td>NA</td>
</tr>
<tr>
<td>P7</td>
<td>V5</td>
<td>5V Power, Pre-Charge</td>
</tr>
<tr>
<td>P8</td>
<td>V5</td>
<td>5V Power</td>
</tr>
<tr>
<td>P9</td>
<td>V5</td>
<td>5V Power</td>
</tr>
<tr>
<td>P10</td>
<td>GND</td>
<td>NA</td>
</tr>
<tr>
<td>P11</td>
<td>DAS/DSS</td>
<td>Device Activity Signal / Disable Staggered</td>
</tr>
<tr>
<td>P12</td>
<td>GND</td>
<td>NA</td>
</tr>
<tr>
<td>P13</td>
<td>NC</td>
<td>NA</td>
</tr>
<tr>
<td>P14</td>
<td>NC</td>
<td>NA</td>
</tr>
<tr>
<td>P15</td>
<td>NC</td>
<td>NA</td>
</tr>
</tbody>
</table>
2.10 Mechanical Dimensions

![Mechanical Dimensions Diagram]

**2.11 Assembly Weight**

An Innodisk SATA Slim 3ME2 within MLC flash ICs, 32GB’s weight is 40 grams approx. The total weight of SSD will be less than 50 grams.

**2.12 Seek Time**

Innodisk SATA Slim 3ME2 is not a magnetic rotating design. There is no seek or rotational latency required.

**2.13 Hot Plug**

The SSD support hot plug function and can be removed or plugged-in during operation. User has to avoid hot plugging the SSD which is configured as boot device and installed operation system.

Surprise hot plug: The insertion of a SATA device into a backplane (combine signal and power) that has power present. The device powers up and initiates an OOB sequence.

Surprise hot removal: The removal of a SATA device from a powered backplane, without first being placed in a quiescent state.

**2.14 NAND Flash Memory**

Innodisk SATA Slim 3ME2 uses Multi Level Cell (MLC) NAND flash memory, which is non-volatility, high reliability and high speed memory storage.
3. Theory of Operation

3.1 Overview

Figure 2 shows the operation of Innodisk SATA Slim 3ME2 from the system level, including the major hardware blocks.

![Innodisk SATA Slim 3ME2 Block Diagram](image)

Innodisk 2 SATA Slim 3ME2 integrates a SATA III controller and NAND flash memories. Communication with the host occurs through the host interface, using the standard ATA protocol. Communication with the flash device(s) occurs through the flash interface.

3.2 SATA III Controller

Innodisk SATA Slim 3ME2 is designed with ID 202, a SATA III 6.0Gbps (Gen. 3) controller. The Serial ATA physical, link and transport layers are compliant with Serial ATA Gen 1, Gen 2 and Gen 3 specification (Gen 3 supports 1.5Gbps/3.0Gbps/6.0Gbps data rate). The controller has 4 channels for flash interface.
3.3 Error Detection and Correction

Highly sophisticated Error Correction Code algorithms are implemented. The ECC unit consists of the Parity Unit (parity-byte generation) and the Syndrome Unit (syndrome-byte computation). This unit implements an algorithm that can correct 66 bits per 1024 bytes in an ECC block. Code-byte generation during write operations, as well as error detection during read operation, is implemented on the fly without any speed penalties.

3.4 Wear-Leveling

Flash memory can be erased within a limited number of times. This number is called the erase cycle limit or write endurance limit and is defined by the flash array vendor. The erase cycle limit applies to each individual erase block in the flash device.

Innodisk SATA Slim 3ME2 uses a static wear-leveling algorithm to ensure that consecutive writes of a specific sector are not written physically to the same page/block in the flash. This spreads flash media usage evenly across all pages, thereby extending flash lifetime.

3.5 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the SSD is shipped, or may develop during the life time of the SSD. When the Bad Blocks is detected, it will be flagged, and not be used anymore. The SSD implement Bad Blocks management, Bad Blocks replacement, Error Correct Code to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit.

3.6 iData Guard

Innodisk’s iData Guard is a comprehensive data protection mechanism that functions before and after a sudden power outage to SSD. Low-power detection terminates data writing before an abnormal power-off, while table-remapping after power-on deletes corrupt data and maintains data integrity. Innodisk’s iData Guard provides effective power cycling management, preventing data stored in flash from degrading with use.

3.7 Garbage Collection/TRIM

Garbage collection and TRIM technology is used to maintain data consistency and perform continual data cleansing on SSDs. It runs as a background process, freeing up valuable controller resources while sorting good data into available blocks, and deleting bad blocks. It also significantly reduces write operations to the drive, thereby increasing the SSD’s speed and lifespan.
4. Installation Requirements

4.1 SATA Slim 3ME2 Pin Directions

![Figure 3: Signal Segment and Power Segment](image)

4.2 Electrical Connections for SATA Slim 3ME2

A Serial ATA device may be either directly connected to a host or connected to a host through a cable. For connection via cable, the cable should be no longer than 1 meter. The SATA interface has a separate connector for the power supply. Please refer to the pin description for further details.

4.3 Device Drive

No additional device drives are required. Innodisk SATA Slim 3ME2 can be configured as a boot device.
### 5. Part Number Rule

<table>
<thead>
<tr>
<th>CODE</th>
<th>1</th>
<th>2</th>
<th>3</th>
<th>4</th>
<th>5</th>
<th>6</th>
<th>7</th>
<th>8</th>
<th>9</th>
<th>10</th>
<th>11</th>
<th>12</th>
<th>13</th>
<th>14</th>
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<td>L</td>
<td>M</td>
<td>3</td>
<td>2</td>
<td>4</td>
<td>D</td>
<td>7</td>
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<td>C</td>
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<td>Q</td>
<td>N</td>
<td>-</td>
<td>X</td>
<td>X</td>
<td></td>
</tr>
</tbody>
</table>

#### Description
- **Code 1st (Disk)**
  - D: Disk

#### Code 2nd ~ 5th (Form Factor)
- **ESLM:** SATA Slim 3ME2

#### Code 7th ~ 9th (Capacity)
- 8G: 8GB
- 16G: 16GB
- 32G: 32GB
- 64G: 64GB
- A28: 128GB
- B56: 256GB

#### Code 10th ~ 12th (Series)
- D72: ID202

#### Code 13th (Flash Mode)
- S: Synchronous flash
- B: Toshiba 15nm Synchronous flash

#### Code 14th (Operation Temperature)
- C: Standard Grade (0°C ~ +70°C)
- W: Industrial Grade (-40°C ~ +85°C)

#### Code 15th (Internal control)
- 1/A: PCB version

#### Code 16th (Channel of data transfer)
- S: Single Channel
- D: Dual Channels
- Q: Quad Channels

#### Code 17th (Flash Type)
- N: Micron MLC
- C: Toshiba MLC

#### Code 19th ~ 20th (Customized Code)
Appendix

Certificate

Issue Date: March 11, 2015
Ref. Report No.: ISL-15LE075CE

Product Name: SATA Slim
Model(s): SATA Slim 3S*#-& ( S:Flash type: (S:SLC,1xSLCM,MLC)/
* Product line: (E.Embedded, G.EverGreen, R.InnoRobust)/
& Product feature: (P. with DRAM, empty: without DRAM))

Responsible Party: Innodisk Corporation
Address: 3F,No.237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221,
Taiwan (R.O.C.)

We, International Standards Laboratory, hereby certify that:

The device bearing the trade name and model specified above has been shown to comply with the applicable technical standards as indicated in the measurement report and was tested in accordance with the measurement procedures specified in European Council Directive-EMC Directive 2004/108/EC. The device was passed the test performed according to:

Standards:
EN 61000-3-3: 2013 and IEC 61000-3-3: 2013
EN 55024: 2010 and CISPR 24: 2010
EN 61000-4-2: 2009 and IEC 61000-4-2: 2008
EN 61000-4-3: 2006+A1: 2008 +A2: 2010 and
EN 61000-4-4:2012 and IEC 61000-4-4:2012

I attest to the accuracy of data and all measurements reported herein were performed by me or were made under my supervision and are correct to the best of my knowledge and belief. I assume full responsibility for the completeness of these measurements and vouch for the qualifications of all persons taking them.

International Standards Laboratory

Jim Chu / Director

[Certificate Image]
Certificate

Issue Date: March 11, 2015
Ref. Report No. ISL-15LE0751

Product Name: SATA Slim
Model(s): SATA Slim 35*#-8 (8-Flash type: 5:SLC, 3:MLC, 2:MLC) /
*:
Product line: (E: Embedded, G: EverGreen, R: InnoRobust) /
&:Product feature: (F: with DRAM, empty: without DRAM)

Applicant: Innodisk Corporation
Address: 5F No. 237, Sec. 1, Datong Rd., Xinzhi Dist., New Taipei City 221,
Taiwan (R.O.C.)

We, International Standards Laboratory, hereby certify that:
The device bearing the trade name and model specified above has been shown to comply with the
applicable technical standards as indicated in the measurement report and was tested in accordance
with the measurement procedures specified. (refer to Test Report if any modifications were made for
compliance).

Standards:
FCC CFR Title 47 Part 15 Subpart B: 2012- Section 15.107 and 15.109
ANSI C63.4-2009
Class B

I attest to the accuracy of data and all measurements reported herein were performed by me or were
made under my supervision and are correct to the best of my knowledge and belief. I assume full
responsibility for the completeness of these measurements and vouch for the qualifications of all
persons taking them.

International Standards Laboratory

Jun Chu / Director

Hi-Chih LAB: No. 85, Gu Dai Kang Street, Hi-Chiah Dist.,
New Taipei City 221, Taiwan
Tel: 886-2-2646-2350; Fax: 886-2-2646-4641

Lung-Tan LAB: No. 120, Lane 180, Hsin Ho Rd., Lung-Tan Dist.,
Tao Yua City 323, Taiwan
Tel: 886-3-407-1718; Fax: 886-3-407-1738
RoHS 自我宣告書 (RoHS Declaration of Conformity)

Manufacturer Product: All Innodisk EM Flash and Dram products

一、 宜鼎國際股份有限公司（以下稱本公司）特此保證售予新漢股份有限公司之所有產品，皆符合歐盟 2011/65/EU 關於 RoHS 之規範要求。

Innomisk Corporation declares that all products sold to Nexcom, are complied with European Union RoHS Directive (2011/65/EU) requirement.

二、 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。

Innomisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

<table>
<thead>
<tr>
<th>Name of hazardous substance</th>
<th>Limited of RoHS</th>
<th>ppm (mg/kg)</th>
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<tbody>
<tr>
<td>銅 (Pb)</td>
<td>&lt; 1000 ppm</td>
<td></td>
</tr>
<tr>
<td>鎳 (Hg)</td>
<td>&lt; 1000 ppm</td>
<td></td>
</tr>
<tr>
<td>鉻 (Cd)</td>
<td>&lt; 100 ppm</td>
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</tr>
<tr>
<td>六價鉻 (Cr 6+)</td>
<td>&lt; 1000 ppm</td>
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<tr>
<td>多溴聯苯 (PBBs)</td>
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</tr>
<tr>
<td>多溴二苯醚 (PBDEs)</td>
<td>&lt; 1000 ppm</td>
<td></td>
</tr>
</tbody>
</table>

立 保 證 書 人 (Guarantor)

Company name  公司名稱： Innodisk Corporation 宜鼎國際股份有限公司

Company Representative  公司代表人： Randy Chien  蔡川勝

Company Representative Title  公司代表人職稱： Chairman  董事長

Date  日期：  2016 / 08 / 04
Manufacturer Product: All Innodisk EM Flash and Dram products

1. 宜鼎國際股份有限公司（以下稱本公司）特此保證此售予貴公司之產品，皆符合歐盟化學品法案（Registration, Evaluation and Authorization of Chemicals; REACH）之規定
   (http://www.echa.europa.eu/de/candidate-list-table last updated: 20/06/2016)。所提供之產品包含：(1) 產品或產品所使用到的所有原物料；(2) 包裝材料；(3) 設計、生產及重工過程中所使用到的所有原物料。

We Innodisk Corporation hereby declare that our products are in compliance with the requirements according to the REACH Regulation

Products include: 1) Product and raw material used by the product; 2) Packaging material; 3) Raw material used in the process of design, production and rework.

2. 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。
InnoDisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

立 保 證 書 人 (Guarantor)

Company name 公司名稱： InnoDisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人： Randy Chien 簡川勝

Company Representative Title 公司代表人職稱： Chairman 董事長

Date 日期： 2016 / 06 / 23